Experimental Options:
Pad Deformation due to Step Change in Wafer
Face to Face Meeting
Cabot Microelectronics, Aurora, IL
October 3, 2003

Polisher
- Pad Type
  - Dyed Freudenberg: __Grooved __Non-grooved
- Platen Speed (RPM)
  - __40 __60 __80 __100 __120 __140
- Wafer Rotation (RPM)
  - __40 __60 __80 __100 __120 __140
- Pressure (PSI)
  - __3 __4 __5 __6 __7 __8
- Conditioner (Diamond Grit)
  - __100 __150 __200 __250
- Conditioner Oscillation (osc/min)
  - __10 __15 __20 __25 __30 __35 __40
- Conditioner Rotation (RPM)
  - __20 __30 __40 __50 __60 __70 __80

Slurry
- Slurry
  - CAB-O-SPERSE
- Slurry Concentration (Water:Slurry)
  - __9:1 __3:2
- Flow Rate (cc/min)
  - __40 __50 __60 __70 __80 __90 __100 __110

Wafer
- Step Change Height (microns)
  - __5 __20 __30 __40 __50 __60 __70 __80 __90 __100

Note: Bold indicates parameters commonly used